## 1. Product profile

### 1.1 General description

Silicon N-channel enhancement mode LDMOS transistor encapsulated in a 2-lead SOT502A flange package with a ceramic cap. The common source is connected to the mounting flange.

Table 1. Test information
Typical RF performance measured in common source class-AB test circuit at $P_{L}=250 \mathrm{~W}$ and 960 MHz to 1215 MHz frequency band. $T_{h}=2{ }^{\circ} \mathrm{C} ; Z_{\text {th( }(-h)}=0.15 \mathrm{~K} / \mathrm{W}$; unless otherwise specified.

| Mode of operation | f <br> (MHz) | $\begin{aligned} & \mathbf{t}_{\mathrm{p}} \\ & (\mu \mathbf{s}) \end{aligned}$ | $\begin{aligned} & \delta \\ & \% \end{aligned}$ | $V_{D S}$ <br> (V) | $P_{L}$ <br> (W) | $\begin{aligned} & \mathbf{G}_{\mathrm{p}} \\ & (\mathrm{~dB}) \end{aligned}$ | $\Delta G_{p}$ <br> (dB) | $\eta_{D}$ <br> (\%) | $\mathbf{P}_{\text {droop(pulse) }}$ <br> (dB) | (ns) | $\begin{aligned} & \mathbf{t}_{\mathrm{f}} \\ & (\mathrm{~ns}) \end{aligned}$ | $Z_{\text {th(j-h) }}$ <br> (K/W) | $\varphi_{\text {ins(rel) }}$ <br> (deg) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| all modes | 960 to 1215 | 100 | 10 | 36 | 250 | 13.5 | 0.8 | 50 | 0.1 | 25 | 6 | 0.18 | $\pm 5$ |
| TCAS | 1030 to 1090 | 32 | 0.1 | 36 | 250 | 14.0 | 0.8 | 50 | 0 | 25 | 6 | 0.07 | $\pm 5$ |
| Mode-S | 1030 to 1090 | 128 | 2 | 36 | 250 | 13.5 | 0.8 | 50 | 0.1 | 25 | 6 | 0.15 | $\pm 5$ |
|  | 1030 to 1090 | 340 | 1 | 36 | 250 | 13.5 | 0.8 | 50 | 0.2 | 25 | 6 | 0.20 | $\pm 5$ |
| JTIDS | 960 to 1215 | 3300 | 22 | 36 | 200 | 13.0 | 1.2 | 45 | 0.2 | 25 | 6 | 0.45 | $\pm 5$ |

## CAUTION

This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

### 1.2 Features and benefits

■ High power gain

- Easy power control
- Excellent ruggedness
- Source on mounting base eliminates DC isolators, reducing common mode inductance.


### 1.3 Applications

■ Avionics transmitter applications in the 960 MHz to 1215 MHz frequency range such as Mode-S, TCAS and JTIDS, DME or TACAN.

## 2. Pinning information

Table 2. Pinning

| Pin | Description | Simplified outline | Graphic symbol |  |
| :--- | :--- | :--- | :--- | :--- |
| 1 | drain | gate |  |  |
| 2 | source |  |  |  |
| 3 |  |  |  |  |

[1] Connected to flange.

## 3. Ordering information

Table 3. Ordering information

| Type number | Package |  |  |
| :--- | :--- | :--- | :--- |
|  | Name | Description | Version |
| BLA0912-250 | - | flanged LDMOST ceramic package; <br> 2 mounting holes; 2 leads | SOT502A |

## 4. Limiting values

Table 4. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
| :--- | :--- | :--- | :--- | :--- | :--- |
| $\mathrm{V}_{\mathrm{DS}}$ | drain-source voltage |  | - | 75 | V |
| $\mathrm{~V}_{\mathrm{GS}}$ | gate-source voltage |  | - | $\pm 22$ | V |
| $\mathrm{P}_{\text {tot }}$ | total power dissipation | $\mathrm{T}_{\mathrm{h}} \leq 25^{\circ} \mathrm{C} ; \mathrm{t}_{\mathrm{p}}=50 \mu \mathrm{~s} ; \delta=2 \%$ | - | 700 | W |
| $\mathrm{~T}_{\text {stg }}$ | storage temperature |  | -65 | +150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{j}}$ | junction temperature |  | - | 200 | ${ }^{\circ} \mathrm{C}$ |

## 5. Thermal characteristics

Table 5. Thermal characteristics

| Symbol | Parameter | Conditions | Typ | Unit |  |
| :--- | :--- | :--- | :--- | :--- | :--- |
| $\mathrm{Z}_{\text {th }(j-\mathrm{h})}$ | transient thermal impedance from junction to <br> heatsink | $\mathrm{T}_{\mathrm{h}}=25^{\circ} \mathrm{C}$ | $\underline{[1]}$ | 0.18 | $\mathrm{~K} / \mathrm{W}$ |

[1] Thermal resistance is determined under RF operating conditions; $\mathrm{t}_{\mathrm{p}}=100 \mu \mathrm{~s}, \delta=10 \%$.

## 6. Characteristics

Table 6. DC characteristics
$T_{j}=25^{\circ}$ C; per section unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
| :--- | :--- | :--- | :--- | :--- | :--- | :--- |
| $\mathrm{V}_{(\mathrm{BR}) \mathrm{DSS}}$ | drain-source breakdown voltage | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V} ; \mathrm{I}_{\mathrm{D}}=3 \mathrm{~mA}$ | 75 | - | - | V |
| $\mathrm{V}_{\mathrm{GS}(\mathrm{th})}$ | gate-source threshold voltage | $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V} ; \mathrm{I}_{\mathrm{D}}=300 \mathrm{~mA}$ | 4 | - | 5 | V |
| $\mathrm{I}_{\mathrm{DSS}}$ | drain leakage current | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V} ; \mathrm{V}_{\mathrm{DS}}=36 \mathrm{~V}$ | - | - | 1 | $\mu \mathrm{~A}$ |
| $\mathrm{I}_{\mathrm{DSX}}$ | drain cut-off current | $\mathrm{V}_{G S}=\mathrm{V}_{G S t h}+9 \mathrm{~V} ;$ | 45 | - | - | A |
|  |  | $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}$ |  |  |  |  |
| $\mathrm{I}_{\mathrm{GSS}}$ | gate leakage current | $\mathrm{V}_{G S}=20 \mathrm{~V} ; \mathrm{V}_{\mathrm{DS}}=0 \mathrm{~V}$ | - | - | 1 | $\mu \mathrm{~A}$ |
| $\mathrm{~g}_{\mathrm{fs}}$ | forward transconductance | $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V} ; \mathrm{I}_{\mathrm{D}}=10 \mathrm{~A}$ | - | 9 | - | S |
| $\mathrm{R}_{\mathrm{DS}(\text { on) }}$ | drain-source on-state resistance | $\mathrm{V}_{\mathrm{GS}}=9 \mathrm{~V} ; \mathrm{I}_{\mathrm{D}}=10 \mathrm{~A}$ | - | 60 | - | $\mathrm{m} \Omega$ |

Table 7. RF characteristics
$R F$ performance in common source class- $A B$ circuit; $T_{h}=25^{\circ} \mathrm{C} ; Z_{t h}=0.15 \mathrm{~K} / \mathrm{W}$; unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $V_{\text {DS }}$ | drain-source voltage |  | - | - | 36 | V |
| f | frequency |  | 960 | - | 1215 | MHz |
| $\mathrm{P}_{\mathrm{L}}$ | output power | $\mathrm{t}_{\mathrm{p}}=100 \mu \mathrm{~s} ; \delta=10 \%$ | 250 | - |  | W |
| $\mathrm{G}_{\mathrm{p}}$ | power gain | $\mathrm{P}_{\mathrm{L}}=250 \mathrm{~W}$ | 12 | 13 |  | dB |
| $\eta_{\mathrm{D}}$ | drain efficiency | $\mathrm{t}_{\mathrm{p}}=100 \mu \mathrm{~s} ; \delta=10 \%$ | 40 | 50 |  | \% |
| $\mathrm{Z}_{\text {th( }(\mathrm{h})}$ | transient thermal impedance from junction to heatsink | $\mathrm{t}_{\mathrm{p}}=100 \mu \mathrm{~s} ; \delta=10 \%$ | - | - | 0.2 | K/W |
| $\mathrm{T}_{\mathrm{h}}$ | heatsink temperature |  | -55 | - | +70 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{P}_{\text {droop(pulse) }}$ | pulse droop power | $\mathrm{t}_{\mathrm{p}}=100 \mu \mathrm{~s} ; \delta=10 \%$ | - | 0.1 | 0.5 | dB |
| $\alpha_{\text {resp(sp) }}$ | spurious response | $V_{S W R}^{\text {load }}$ = $2: 1$ | - | - | -60 | dBc |
| $\mathrm{t}_{\mathrm{r}}$ | rise time |  | - | 25 | 50 | ns |
| $\mathrm{t}_{\mathrm{f}}$ | fall time |  | - | 6 | 25 | ns |

### 6.1 Ruggedness in class-AB operation

The BLA0912-250 is capable of withstanding a load mismatch corresponding to $\mathrm{VSWR}=5: 1$ through all phases under the following conditions: $\mathrm{V}_{\mathrm{DS}}=36 \mathrm{~V}$; $\mathrm{f}=960 \mathrm{MHz}$ to 1215 MHz at rated load power.

## 7. Application information

### 7.1 Impedance information

Table 8. Typical impedance
Typical values per section unless otherwise specified.

| $\mathbf{f}$ | $\mathbf{Z}_{\mathbf{S}}$ | $\mathbf{Z}_{\mathbf{L}}$ |
| :--- | :--- | :--- |
| $\mathbf{M H z}$ | $\Omega$ | $\Omega$ |
| 960 | $0.89-\mathrm{j} 1.70$ | $1.53-\mathrm{j} 1.13$ |
| 1030 | $1.37-\mathrm{j} 1.23$ | $1.47-\mathrm{j} 0.99$ |
| 1090 | $2.09-\mathrm{j} 1.27$ | $1.38-\mathrm{j} 0.85$ |
| 1140 | $2.40-\mathrm{j} 1.97$ | $1.30-\mathrm{j} 0.71$ |
| 1215 | $1.51-\mathrm{j} 2.61$ | $1.17-\mathrm{j} 0.47$ |



Fig 1. Definition of transistor impedance

### 7.2 Application circuit



See Table 9 for details of striplines.
Fig 2. Layout of class-AB application circuit

Table 9. Layout details
See Figure 2.
Striplines are on a Rodgers Duroid 6010 Printed-Circuit Board (PCB); $\varepsilon_{r}=10.2$ F/m;
thickness $=0.64 \mathrm{~mm}$

| Component | Description | Dimensions |
| :---: | :---: | :---: |
| Input circuit |  |  |
| L1 | stripline | $5 \mathrm{~mm} \times 0.8 \mathrm{~mm}$ |
| C1 | stripline | $1.2 \mathrm{~mm} \times 3.5 \mathrm{~mm}$ |
| L2 | stripline | capacitor pad: $1 \mathrm{~mm} \times 1 \mathrm{~mm}(1 \times$ ) |
|  |  | curve: width 0.8 mm ; angle $90^{\circ}$; radius 0.8 mm (10×) |
|  |  | vertical: $3.9 \mathrm{~mm} \times 0.8 \mathrm{~mm}(2 \times)$ |
|  |  | vertical: $9.4 \mathrm{~mm} \times 0.8 \mathrm{~mm}(3 \times)$ |
|  |  | horizontal: $0.5 \mathrm{~mm} \times 0.8 \mathrm{~mm}(4 \times)$ |
| L3 | stripline | $3 \mathrm{~mm} \times 2 \mathrm{~mm}$ |
| C2 | stripline | $4 \mathrm{~mm} \times 6.5 \mathrm{~mm}$ |
| L4 | stripline | $5 \mathrm{~mm} \times 1 \mathrm{~mm}$ |
| C3 | stripline | $8.8 \mathrm{~mm} \times 30 \mathrm{~mm}+0.2 \mathrm{~mm} \times 13 \mathrm{~mm}$ |
| Output circuit |  |  |
| C4 | stripline | $0.2 \mathrm{~mm} \times 13 \mathrm{~mm}+19 \mathrm{~mm} \times 17.1 \mathrm{~mm}$ |
| L5 | stripline | $2.5 \mathrm{~mm} \times 2.3 \mathrm{~mm}$ |
| L6 | stripline | $4 \mathrm{~mm} \times 1 \mathrm{~mm}$ |
| C5 | stripline | $3 \mathrm{~mm} \times 6.6 \mathrm{~mm}$ |
| L7 | stripline | curve: width 0.8 mm ; angle $90^{\circ}$; radius $0.8 \mathrm{~mm}(6 \times$ ) |
|  |  | vertical: $2.2 \mathrm{~mm} \times 0.8 \mathrm{~mm}(2 \times)$ |
|  |  | vertical: $6 \mathrm{~mm} \times 0.8 \mathrm{~mm}(1 \times)$ |
|  |  | horizontal: $1 \mathrm{~mm} \times 0.8 \mathrm{~mm}(2 \times)$ |
| L8 | stripline | $2.5 \mathrm{~mm} \times 0.8 \mathrm{~mm}$ |
| $1 / 4 \lambda$ line | stripline | curve: width 1 mm ; angle $90^{\circ}$; radius 0.8 mm |
|  |  | vertical: $5 \mathrm{~mm} \times 1 \mathrm{~mm}$ |
|  |  | horizontal: $19 \mathrm{~mm} \times 1 \mathrm{~mm}$ |



Dimensions in mm .
See Table 10 for list of components.
Fig 3. Component layout for class-AB application circuit

Table 10. List of components
See Figure 3.

| Component | Description | Value | Remarks |  |
| :--- | :--- | :--- | :--- | :--- |
| C1, C3, C9 | multilayer ceramic chip capacitor | 1 nF | $\underline{[1]}$ |  |
| C2, C6, C10 | multilayer ceramic chip capacitor | 22 pF | $\underline{[2]}$ |  |
| C4 | tantalum SMD capacitor | $47 \mu \mathrm{~F} ; 20 \mathrm{~V}$ | KEMET: T491D476M020AS |  |
| C5 | multilayer ceramic chip capacitor | 56 pF | $\underline{[2]}$ |  |
| C7 | multilayer ceramic chip capacitor | 47 pF | $\underline{[2]}$ |  |
| C8 | tantalum SMD capacitor | $22 \mu \mathrm{~F} ; 63 \mathrm{~V}$ |  |  |
| R1 | SMD resistor | $51 \Omega$ | 0805 |  |
| R2 | resistor | $49.9 \Omega$ |  |  |

[1] American Technical Ceramics type 100B or capacitor of same quality.
[2] American Technical Ceramics type 100A or capacitor of same quality.

## 8. Test information

### 8.1 RF performance

Typical RF performance measured in common source class-AB test circuit at $P_{L}=250 \mathrm{~W}$ and 960 MHz to 1215 MHz frequency band. $\mathrm{T}_{\mathrm{h}}=25^{\circ} \mathrm{C} ; \mathrm{Z}_{\text {th }(\mathrm{j}-\mathrm{h})}=0.15 \mathrm{~K} / \mathrm{W}$; unless otherwise specified.


Fig 4. Power gain and drain efficiency as function of frequency; typical values


$$
\begin{aligned}
& \mathrm{T}_{\mathrm{h}}=25^{\circ} \mathrm{C} ; \mathrm{V}_{\mathrm{DS}}=36 \mathrm{~V} ; \mathrm{I}_{\mathrm{Dq}}=150 \mathrm{~mA} ; \text { class-AB; } \\
& \mathrm{t}_{\mathrm{p}}=100 \mu \mathrm{~s} ; \delta=10 \% .
\end{aligned}
$$

(1) $f=960 \mathrm{MHz}$
(2) $f=1030 \mathrm{MHz}$
(3) $f=1090 \mathrm{MHz}$
(4) $f=1140 \mathrm{MHz}$
(5) $f=1215 \mathrm{MHz}$

Fig 5. Power gain as a function of load power; typical values


## 9. Package outline

Flanged ceramic package; 2 mounting holes; 2 leads

$\phi \mid \mathrm{w}_{1}(\mathbb{M} \mid \mathrm{A}(\mathrm{M}) \mathrm{B}(\mathrm{M}$


DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

| UNIT | $\mathbf{A}$ | $\mathbf{b}$ | $\mathbf{c}$ | $\mathbf{D}$ | $\mathbf{D}_{\mathbf{1}}$ | $\mathbf{E}$ | $\mathbf{E}_{\mathbf{1}}$ | $\mathbf{F}$ | $\mathbf{H}$ | $\mathbf{L}$ | $\mathbf{p}$ | $\mathbf{Q}$ | $\mathbf{q}$ | $\mathbf{U}_{\mathbf{1}}$ | $\mathbf{U}_{\mathbf{2}}$ | $\mathbf{w}_{\mathbf{1}}$ | $\mathbf{w}_{\mathbf{2}}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | 4.72 | 12.83 | 0.15 | 20.02 | 19.96 | 9.50 | 9.53 | 1.14 | 19.94 | 5.33 | 3.38 | 1.70 | 27.94 | 34.16 | 9.91 | 0.25 | 0.51 |
|  | 3.43 | 12.57 | 0.08 | 19.61 | 19.66 | 9.30 | 9.25 | 0.89 | 18.92 | 4.32 | 3.12 | 1.45 |  | 33.91 | 9.65 |  |  |
| inches | 0.186 | 0.505 | 0.006 | 0.788 | 0.786 | 0.374 | 0.375 | 0.045 | 0.785 | 0.210 | 0.133 | 0.067 | 1.100 | 1.345 | 0.390 | 0.01 | 0.02 |
|  | 0.135 | 0.495 | 0.003 | 0.772 | 0.774 | 0.366 | 0.364 | 0.035 | 0.745 | 0.170 | 0.123 | 0.057 |  | 1.335 | 0.380 |  |  |


| OUTLINE VERSION | REFERENCES |  |  | EUROPEAN PROJECTION | ISSUE DATE |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | IEC | JEDEC | JEITA |  |  |
| SOT502A |  |  |  | $\square$ (-) | $\begin{aligned} & -03-01-10 \\ & 12-05-02 \end{aligned}$ |

Fig 8. Package outline SOT502A

## 10. Abbreviations

Table 11. Abbreviations

| Acronym | Description |
| :--- | :--- |
| DC | Direct Current |
| DME | Distance Measuring Equipment |
| JTIDS | Joint Tactical Information Distribution System |
| LDMOS | Laterally Diffused Metal-Oxide Semiconductor |
| LDMOST | Laterally Diffused Metal-Oxide Semiconductor Transistor |
| Mode-S | Mode Select |
| RF | Radio Frequency |
| SMD | Surface Mounted Device |
| TACAN | TACtical Air Navigation |
| TCAS | Traffic Collision Avoidance System |
| VSWR | Voltage Standing-Wave Ratio |

## 11. Revision history

Table 12. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
| :--- | :--- | :--- | :--- | :--- |
| BLA0912-250\#4 | 20150901 | Product data sheet | - | BLA0912-250 v.3 |
| Modifications: | - The format of this document has been redesigned to comply with the new identity guidelines <br> of Ampleon. <br> $\bullet$ |  |  |  |
| BLA0912-250 v.3 | 20101126 | Product data sheet | - | BLA0912-250_2 |
| BLA0912-250_2 | 20040722 | Product data sheet | - | BLA0912-250_N_1 |
| BLA0912-250_N_1 | 20031024 | Preliminary data sheet | - | 9397 750 12224 |

## 12. Legal information

### 12.1 Data sheet status

| Document status $\underline{[1][2]}$ | Product $\boldsymbol{\text { status }} \underline{[3]}$ | Definition |
| :--- | :--- | :--- |
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